

Radlan - Technology Case Study

Challenge: Position Radlan's OpENS (Open Embedded Networking System) solution as the leading SoC for major chip makers

- Educate the engineering trade on Radlan's OpENS product who were convinced a "box-less router" did not apply to their readership



- Work internationally with Israel for weekly meetings, in-person brain storming sessions and press/analyst calls

- Finding the right audience between the decision makers and the engineering teams who would understand this advanced system to create better, faster chips for the ultimate - "gig to the desktop"

Strategy (Phase I)

- Meet in Israel with the team and begin brainstorming everything from timing to naming of the product. After 16 straight hours, OpENS was the agreed upon name and used for every Radlan product for the first phase of development. Collateral was prepared and we set out on a press/analyst tour with Radlan's President and Head of Engineering (New York, Boston and San Francisco).

- Our strategy was to utilize Radlan's Broadcom relationship to elevate their status and to highlight their OpENS product as a viable player in the embedded systems market. Relationships were made and a leading editor that we met with highlighted them as a major player in the key trade, EE Times. He also covered them at the key trade show for embedded network companies, Network+Interop.

Strategy (Phase II)

- Secure customer spokespeople from Broadcom and Marvell and negotiate quotes for product announcement.

- Create press release on OpENS, using the customer quotes and analyst backing of product, (obtained while on previous tour) and secure press coverage with interviews prior to announce date. Result - Day of announce coverage in EE Times, Integrated Systems Design, LightReading, Integrated Communications Design and online coverage.

Results

- **Analyst Quote in Launch Release:** *"Networking chip suppliers are providing increasingly complete solutions to their customers. An important aspect of a complete solution is software. However, internally developing all of the requisite software is not always practical. In these cases, chip vendors will partner with companies with specialized software expertise."*

- said Joseph Byrne, analyst at Gartner Dataquest

- Message: With the Radlan system, chip makers can focus on time-to-market advantage with the prepackaged OpENS solution by Radlan.

- Result: Radlan becomes the highest profiled company of the RAD Group spin-offs.
- Additional Highlights: Speaking engagements in the U.S. at shows such as CommDesign, Next Generation Networks Conference and SuperComm
 - White paper coverage on online trades
 - Bylines articles placed in EE Times and ICD

Media Coverage: TOTAL GROSS IMPRESSIONS: 6, 531, 455

Electronic Engineering Times

June 16, 2002

[Gigabit Ethernet to the Desktop](#)

by Zion Benodis, Product Marketing Director



June 4, 2002

[Switching to a Faster Giga Switch](#)

by Zion Benodis, Product marketing Director

EE TIMES

May 7, 2002

[Radlan rolls out reference designs](#)

by Loring Wirbel



February 14, 2002

[Script/simulation approach speeds SoC verification](#)

by Michael Orr, vice president of technology and product management

EE TIMES

February 8, 2002

[Reconfiguring for broadband access](#)

by Michael Orr, vice president of technology and product management

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